

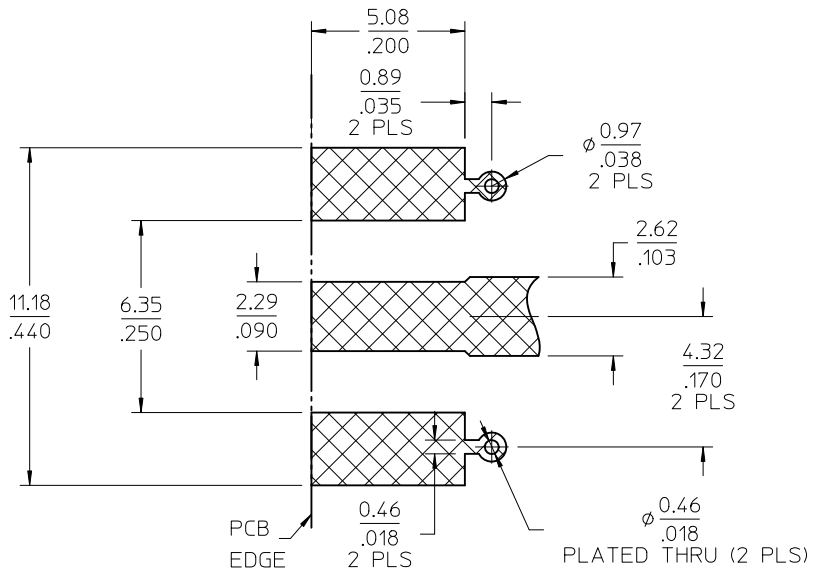
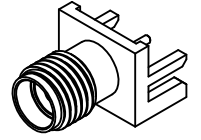
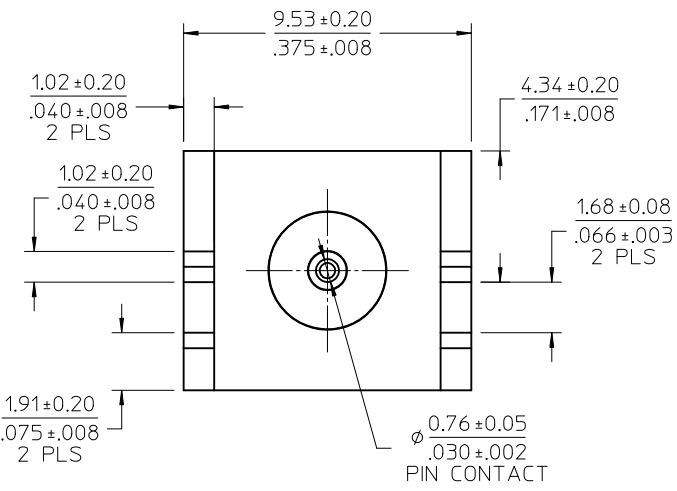
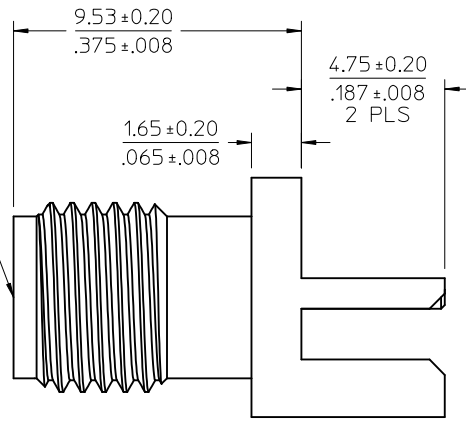
MATERIALS AND FINISHES

BODY BRASS
PLATED GOLD (SEE TABLE)

CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)

INSULATOR TEFLON

SMA JACK
INTERFACE



RECOMMENDED MOUNTING PAD

BASE WIDTH: 9.53(.375)
BOARD THICKNESS: 1.57(.062)
BOARD MATERIAL: FR4 W/28 g(1.0 OZ) COPPER
ON BOTTOM (GROUND) SIDE

PS-89675-2820	ELEC/MECH PERFORMANCE
MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

73251-1153	GOLD FLASH	GOLD 5μ"	TRAY (80 PIECES)
73251-1152	GOLD	GOLD	TRAY (20 PIECES)
73251-1151	GOLD	GOLD	ONE 73251-1150 PER BAG
73251-1150	GOLD	GOLD	TRAY (80 PIECES)
PART NO.	BODY PLATING	CONTACT PLATING	PACKAGING
DIM X			

CHG: ADDED -1153 PER PDR1103766 IEC NO: URF2012-0213 DRW: CME102 2011/03/23 CHKD: APPR: M HUANG 2011/12/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- ANGULAR ± 2 °	MM/IN		METRIC		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE TEF 2002/06/27 CHECKED BY DATE SSS 2002/06/27 APPROVED BY DATE GMH 2002/06/27	TITLE			
			MATERIAL NO.	DOCUMENT NO.			

SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	SMA JACK, EDGE MOUNT 50 OHMS, EWR-1764 SMA-J/PCB MOLEX INCORPORATED SD-73251-115 SHEET NO. 1 OF 1
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